DEPFET cooling

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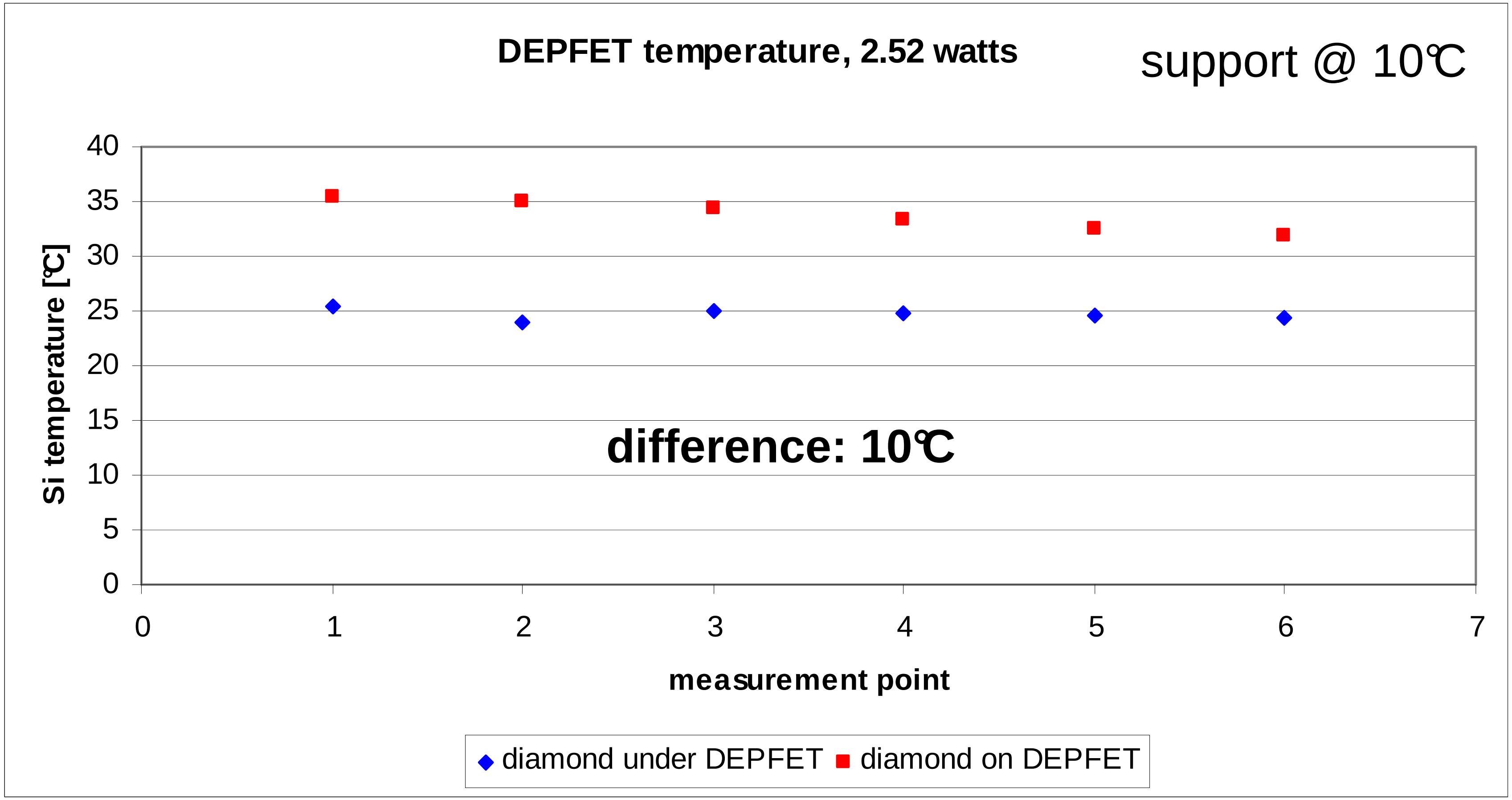
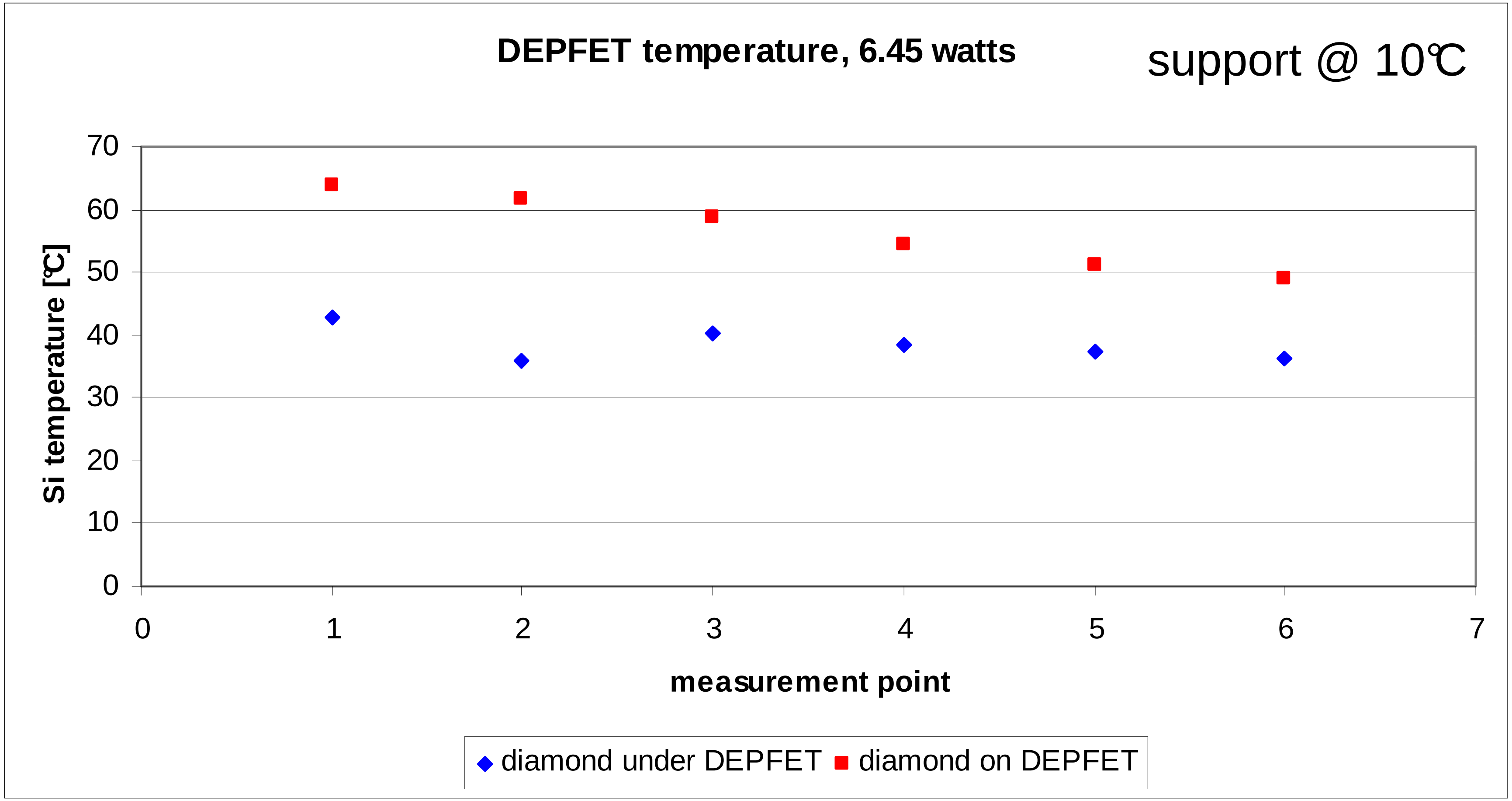
1. results from measurements

- diamond on top of DEPFET, ***without TPG-foil***
- results for 2.5, 3.6, 4.9 and 6.5 watts



1. results from measurements

- highest power consumption: 6.45 watts (<< 9W!)
- difference now about 20℃!



2. workpackage

- separation of our workpackage in two parts:
- 1. Karlsruhe:
  simulation and measurements of „diamond on top with TPG-foil“
- 2. Valencia:
  simulation and measurements of „diamond under DEPFET and chips“

- also to be done:
  simulations of impact of both solutions on physics performance!

3. TPG-foil

- the TPG-foil purchased by Karlsruhe turned out to be unusable (not flexible)
- last week: meeting with representatives from Optigraph
- we now have new samples of TPG-foil (80µm thick)

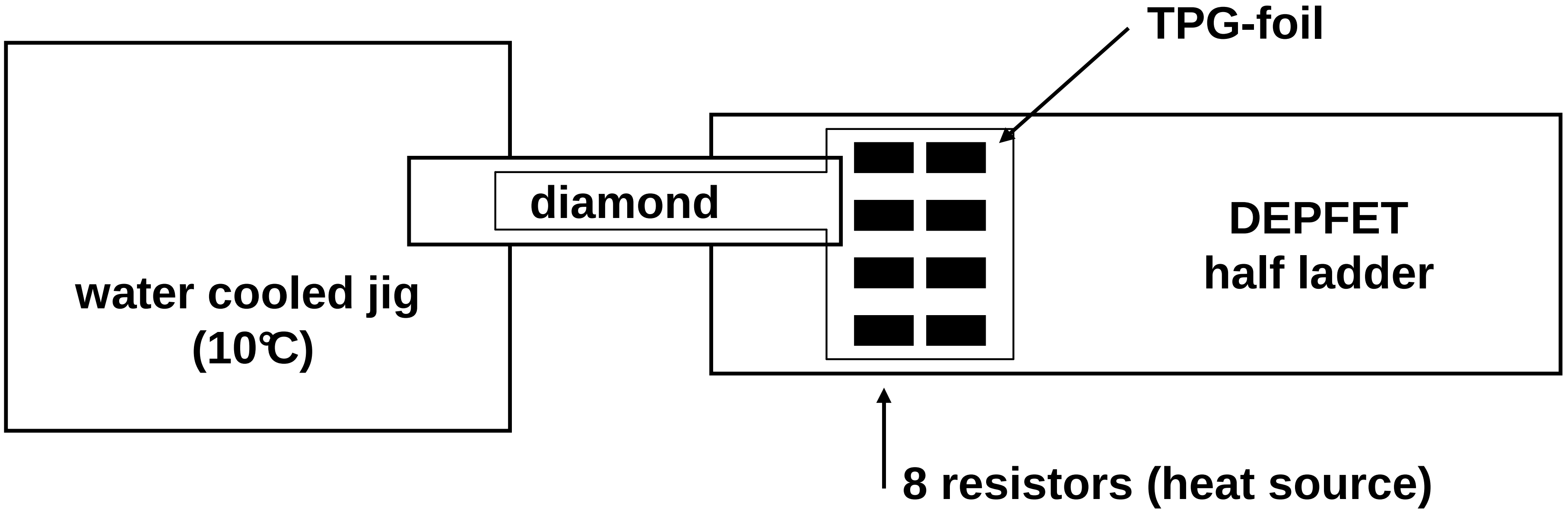
- even new type of foil is like „normal TPG“!
- same problems:
  mechanical stability and flexibility
- production of curved surface still difficult

3. TPG-foil

- simulations done in Karlsruhe show that minimum thickness of TPG-foil is ~200µm
- new measurements with 80, 160 and 240µm of TPG between chips and diamond
- trying to have results with new TPG-foil ready for Barcelona meeting

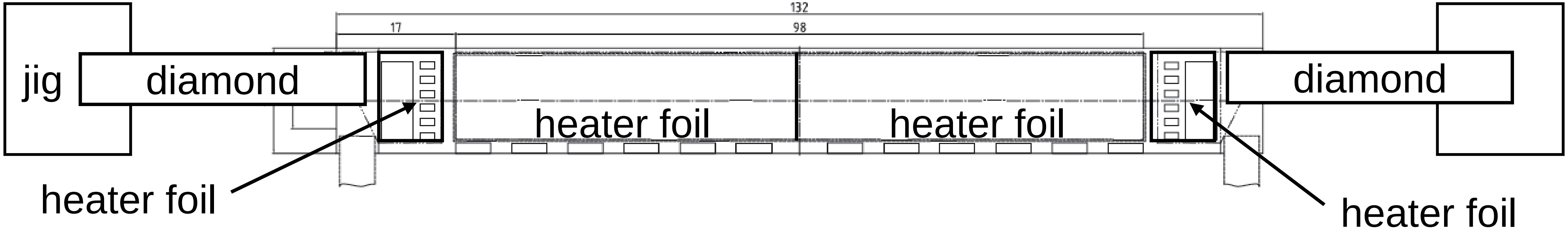
4. current measurements

- only two weeks to Barcelona meeting!!!
- no time to build new measurement setup
  → use old setup again!



5. new setup in October

- new setup postponed to October



- complete ladder
- 2 new cooling jigs (to be manufactured)
- long Si-strip (available)
- 4 heater foils (ordered)
- second CVD-diamond (ordered)